

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| S1 | 42 | "257"/\$.ccls. and UBM and adhesive and substrate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/03 09:45 |
| S2 | 42 | "257"/\$.ccls. and (UBM or (under adj ball adj metallurgy)) and adhesive and substrate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/22 18:00 |
| S3 | 64 | "257"/\$.ccls. and (UBM or (under adj ball adj (metallurgy or metallization))) and (adhesive or epoxy) and substrate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/22 18:20 |
| S4 | 74 | "438"/\$.ccls. and (UBM or (under adj ball adj (metallurgy or metallization))) and (adhesive or epoxy) and substrate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/22 18:47 |
| S5 | 338 | 438/106.ccls. and @pd>"20020520" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/22 19:03 |
| S6 | 266 | 438/108.ccls. and @pd>"20020520" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/22 19:10 |
| S7 | 80 | 438/614.ccls. and @pd>"20020520" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/22 19:14 |
| S8 | 133 | 257/783.ccls. and @pd>"20020520" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/22 19:15 |
| S9 | 2 | "20010021541".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/23 15:02 |
| S10 | 2 | "6355507".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/03/23 15:02 |

| | | | | | | |
|-----|------|--|---|----|-----|------------------|
| S11 | 109 | (polymer or polymeric) with (bismaleimide adj triazine) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/01/08 10:01 |
| S12 | 81 | ((polymer or polymeric) with (bismaleimide adj triazine)) and adhesive | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/15 20:31 |
| S13 | 2 | ((polymer or polymeric) with (bismaleimide adj triazine)) and (adhesive with (microns micrometers)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/15 20:34 |
| S14 | 19 | ((polymer or polymeric) with (bismaleimide adj triazine)) and (adhesive with thick\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/15 20:40 |
| S15 | 4695 | ((polymer or polymeric) with (substrate)) and (adhesive with thick\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/15 20:40 |
| S16 | 168 | ((polymer or polymeric) with (substrate)) with (adhesive near5 thick\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/15 20:41 |
| S17 | 114 | "257"/\$.ccls. and singulation with saw\$3 and @ad<"20010330" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/17 13:07 |
| S18 | 149 | "257"/\$.ccls. and (substrate with (bismaleimide adj triazine)) and @ad<"20010330" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/17 13:20 |
| S19 | 13 | "257"/\$.ccls. and (substrate with (polymer polymeric) with (bismaleimide adj triazine)) and @ad<"20010330" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/17 13:16 |
| S20 | 17 | "257"/\$.ccls. and (adhesive with polyimide with thermocompress\$3) and @ad<"20010330" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/17 13:17 |

| | | | | | | |
|-----|-------|--|---|----|-----|------------------|
| S21 | 0 | "257"/\$.ccls. and (substrate with (bismaleimide adj triazine)) and (adhesive with polyimide with thermocompress\$3) and @ad<"20010330" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/17 13:21 |
| S22 | 0 | "257"/\$.ccls. and (substrate with (polymer polymeric)) and (adhesive with polyimide with thermocompress\$3) and @ad<"20010330" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/17 13:21 |
| S23 | 16888 | (die chip) same substrate same (adhesive adhesion) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/05/05 16:13 |
| S24 | 1695 | (die chip) same substrate same (adhesive adhesion) and (singulation saw sawing) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/05/06 16:16 |
| S25 | 412 | (die chip) same substrate same (opening openings via) same (adhesive adhesion) and (singulation saw sawing) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/05/06 16:18 |
| S26 | 33 | ((("20020163055") or ("20020170746") or ("5882956") or ("20010021541") or ("6355507") or ("6265782") or ("6232147") or ("5480835") or ("5846875") or ("20010021541") or ("6355507") or ("6265782") or ("6232147") or ("5480835") or ("5846875") or ("6064114") or ("6075710") or ("5994766") or ("6118183") or ("6137164") or ("5734201") or ("5914533"))).PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/25 13:40 |
| S27 | 239 | "257"/\$.ccls. and UBM and adhesive and substrate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/03 09:46 |
| S28 | 51672 | "257"/\$.ccls. and UBM (die chip) and (substrate with (opening via)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/03 09:47 |
| S29 | 286 | "257"/\$.ccls. and UBM and (die chip) and (substrate with (opening via)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/03 09:54 |

| | | | | | | |
|-----|-------|--|---|----|----|------------------|
| S30 | 286 | "257"/\$.ccls. and UBM and (die chip) and (substrate with (opening via throughhole through-hole)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/03 10:58 |
| S31 | 187 | "438"/\$.ccls. and UBM and (die chip) and (substrate with (opening via throughhole through-hole)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/03 10:46 |
| S32 | 38 | "438"/\$.ccls. and UBM and (die chip) and (substrate with hole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/03 10:49 |
| S33 | 59 | "257"/\$.ccls. and UBM and (die chip) and (substrate with hole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/03 10:49 |
| S34 | 12525 | "257"/\$.ccls. and (copper cu nickel ni) and (die chip) and (substrate with (opening via throughhole through-hole)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/03 10:59 |
| S35 | 2875 | "257"/\$.ccls. and ((die chip) with (copper cu nickel ni)) and (substrate with (opening via throughhole through-hole)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/03 10:59 |